

Bonding

Durability through bonding is crucial when it comes to part reliability. One of E-Fab's promises is to deliver accurate metal parts to exacting specifications and tight tolerances. That promise is significant for flex, electronic, and thin metal circuits in high-technology applications.

E-Fab utilizes Thermocompression Bonding — a combination of heat and pressure from a hydraulic press — to compress and bond lamination layers, joining metals to different substrates. Multilayer laminations add mechanical strength, design possibilities, and flexibility.

E-Fab's Precision Bonding Processes and Advantages

Bonding is a crucial manufacturing process when creating parts for telecommunications, technology, and defense customers.

Conductivity	Bonding does not impede the flow of electricity.
Electrical Insulation	Circuit boards and electrical equipment have excellent electrical insulation.
Mechanical Strength	Thermocompression bonding delivers stronger parts that are reliable and durable.
Environmental Benefits	The result of the bonding process creates little to no waste and is environmentally friendly.
Power Distribution	Increases the power distribution area, enhancing part performance.
Superior TCE Match	Parts have a better TCE match with silicon after thermocompression bonding.

Bonding Expertise at E-Fab

Typical Parts	Antenna Substrates, Microwave Components, MRI Machine Parts, Multilayer Busbars, RF Shields, EMI Shields, Control Circuits, OEM Products, Flex Cable Batteries, Semiconductors, Hybrid Semiconductors, Flex Circuits, Sensors, and Flex Heaters
Materials	Kapton
Metals	Aluminum, Copper, Stainless Steel, Steel, and more
Industries Served	Aerospace, Military, Defense, Energy, Fuel Cells, Medical, Microwave, Semiconductor, Telecommunications, Colleges, Secondary Schools, Federal Agencies, State Government, Agriculture, Automotive/Transportation/Mobility, Electronics, Instrumentation & Control Systems, Manufacturing, Technology

Our Certifications



ISO 9001:2015



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